Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-8. (Canceled)

9. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

~~(a) providing a source of laser radiation having a wavelength between about 600 and 1000 nm;~~

~~(b) providing a thermally curable liquid organic matrix including at least one material that is light absorbing at the wavelength of the laser radiation;~~

~~(c)~~ (a) depositing an amount of thermally curable epoxy compound on the electronic component sufficient ~~of said liquid organic matrix~~ to form a layer thereof covering the component, the epoxy compound having included therein at least one light absorbing material; and

~~(d)~~ (b) directing ~~said~~ laser radiation having a wavelength between about 600 and 1000 nm onto the layer of ~~liquid organic matrix~~ thermally curable epoxy compound for a time period sufficient that the light absorbing material absorbs a portion of the laser radiation and generates heat in the layer whereby the epoxy compound ~~liquid organic matrix~~ is cured.

10. (Original) The method of claim 9, wherein said light absorbing material is carbon black.

11. (Original) The method of claim 9, wherein said light absorbing material is a dye.

12. (Original) The method of claim 9, wherein said light absorbing material is a powdered metal.

13. (Currently Amended) The method of claim 9, wherein said laser radiation ~~source is a diode-laser array and said laser radiation~~ has a wavelength of about 808 nm.

14. (Currently Amended) The method of claim 9, wherein said laser radiation is produced by a diode-laser array ~~said thermally convertible liquid matrix is an epoxide and said light absorbing material is carbon black~~.

15. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) providing a diode-laser array for delivering radiation laser radiation having a wavelength between about 600 and 1000 nm;

(b) providing a thermally curable liquid epoxy compound ~~organic matrix~~ having included therein at least one material that is strongly absorbing for the wavelength of the laser radiation;

(c) depositing on the electronic component a sufficient amount of said liquid epoxy compound ~~organic matrix~~ to form a layer thereof covering the component; ~~and~~

(d) transporting said laser radiation from said diode-laser array, via an optical fiber bundle, to an optical projector for projecting said laser radiation; and

(e) projecting said laser radiation onto said layer of liquid epoxy compound ~~light-absorbing material containing, liquid organic matrix~~ for a time period sufficient that the light absorbing material absorbs a portion of the laser radiation and generates heat in the layer whereby the liquid epoxy compound ~~liquid organic matrix~~ is cured.

16. (Currently Amended) The method of claim 15, wherein said laser radiation has a wavelength of about 808 nm ~~said liquid organic matrix is an epoxide~~.

17. (Original) The method of claim 15, wherein said at least one light absorbing material is carbon black.

18. (Currently Amended) The method of claim 15, wherein during step (e) said integrated circuit component is held in a fixed relationship to said optical projector and said laser radiation is projected onto said liquid epoxy compound ~~organic~~ layer in the form of a spot having a size sufficient to at least cover the electronic component.

19. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

~~(a) providing a diode laser array for delivering radiation laser radiation having a wavelength between about 600 and 1000 nm;~~

~~(b) providing a thermally curable liquid organic matrix at least one material that light absorbing at the wavelength of the laser radiation;~~

~~(c)~~ (a) depositing on the electronic component an amount of thermally curable epoxy compound sufficient ~~of said light absorbing material containing liquid organic matrix~~ to form a layer thereof covering the component, the epoxy compound having included therein at least one light absorbing material;

~~(d)~~ (b) directing ~~said~~ laser radiation having a wavelength between about 600 and 1000 nm ~~from said diode laser array~~ into an optical projector arranged to project said laser radiation in the form of a line of said laser radiation;

~~(e)~~ (c) projecting said line of laser radiation onto said layer of epoxy compound including the light absorbing material ~~containing liquid organic matrix~~; and

~~(f)~~ (d) during step ~~(e)~~ (c), moving the substrate and said ~~light absorbing material containing, liquid epoxide layer covered,~~ integrated circuit ~~thereon~~ with respect to said optical projector such that said ~~light absorbing material containing, liquid epoxide~~ epoxy compound layer on the integrated circuit is exposed to said radiation for a time sufficient that said light absorbing material absorbs a portion of the laser radiation and generates heat in the layer whereby the liquid epoxy compound ~~containing, liquid epoxide layer~~ is cured.

20. (Currently Amended) The method of claim 19, wherein said laser radiation is produced by a diode-laser array ~~said liquid organic matrix is an epoxide~~.

21. (Original) The method of claim 19, wherein said at least one light absorbing material is carbon black.

22. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) depositing on the electronic component a thermally curable liquid ~~organic matrix~~ epoxide layer including therein at least one light absorbing material; and

(b) irradiating the epoxide layer ~~matrix~~ with laser light generated by a laser diode array and having a wavelength between 600 and 100nm, the epoxide layer ~~the matrix~~ being formulated so that at least 15% of the radiation striking the epoxide layer ~~the matrix~~ is absorbed by the at least one light absorbing material ~~therein~~ in a manner to heat and cure the epoxide layer ~~the matrix~~.